



100% Material Declaration Data Sheet PC44

PK159 (v1.2) September 29, 2006

Material Declaration Data Sheet

Average Weight: 2.360 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.00764	0.32%
	Silicon	7440-21-3	100%		0.007637	
Die Attach Material					0.00199	0.08%
	Resin	Trade Secret	25.00		0.000498	
	Silver	7440-22-4	75.00		0.001494	
Mold Compound					1.82599	77.38%
	Epoxy Resin (EP)	Trade Secret	7.50		0.0136949	
	Silica	60676-86-0	86.00		1.570352	
	Carbon Black	1333-86-4	0.50		0.009130	
	Epoxy Cresol Novolac	Trade Secret	2.00		0.036520	
	Phenolic Resin	Trade Secret	4.00		0.073040	
Leadframe					0.49849	21.13%
	Copper	7440-50-8	99.90		0.497994	
	Zirconium	7440-67-7	0.10		0.000498	
Leadframe Plating					0.00149	0.06%
	Silver	7440-22-4	100.00			
Bond Wire					0.00182	0.08%
	Gold	7440-57-5	100.00		0.001818	
Ext. Plating					0.02221	0.94%
	Tin	7440-31-5	85.00		0.0188785	
	Lead	7439-92-1	15.00		0.0033315	

Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/08/06	1.0	Initial release.
7/12/06	1.1	100% Material Declaration.
9/29/06	1.2	Updated component descriptions.